

(Table 1)

		Heat cycle test					Dissolu- tion of conductor circuit
		Crack of interlaminar insulating resin layer		Peeling of via hole		Peel strength	
		1000 cycles	2000 cycles	1000 cycles	2000 cycles		
Example	1	none	none	none	none	1.2kg/cm	presence
	2	none	none	none	none	1.2kg/cm	presence
	3	none	none	none	none	1.2kg/cm	none
	4	none	none	none	none	1.0kg/cm	none
	5	none	none	none	none	1.0kg/cm	none
	6-1	none	none	none	none	1.0kg/cm	none
	6-2	none	none	none	none	1.0kg/cm	none
	6-3	none	none	none	none	1.0kg/cm	none
	6-4	none	none	none	none	1.0kg/cm	none
	6-5	none	none	none	none	1.0kg/cm	none
	6-6	none	none	none	none	1.0kg/cm	none
	6-7	none	none	none	none	1.0kg/cm	none
	6-8	none	none	none	none	1.0kg/cm	none
6-9	none	none	none	none	1.0kg/cm	none	
6-10	none	none	none	none	1.0kg/cm	none	
Comparative Example 1		none	presence	none	presence	0.9kg/cm	presence
Comparative Example 2		none	presence	none	presence	0.9kg/cm	none

Industrial Applicability

As mentioned above, according to the invention, it is possible to prevent the occurrence of cracks and the conductor peeling in the interlaminar insulating layer and dissolution of the conductor circuit due to the local electrode reaction. so